L Number	Hits	Search Text	DB	Time stamp
10	2	(US-20020074381-$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:16
11	2	((US-20020074381-$).did.) and (in or indium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:52
12	14	(("6087021") or ("5812925") or ("4325734") or ("5621607") or ("3602979") or ("4614296") or ("6520401") or ("6187450") or ("5392982") or ("5542602") or ("6199751") or ("6340113") or ("5009360") or ("5025304")).PN.	USPAT	2003/09/16 12:53
13	10	((("6087021") or ("5812925") or ("4325734") or ("5621607") or ("3602979") or ("4614296") or ("6520401") or ("6187450") or ("5392982") or ("5542602") or ("6199751") or ("6340113") or ("5009360") or ("5025304")).PN.) and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:16
14	10	(US-6340113-$ or US-6199751-$ or US-6087021-$ or US-5812925-$ or US-5621607-$ or US-5542602-$ or US-5392982-$ or US-5025304-$ or US-5009360-$ or US-4325734-$).did.	USPAT	2003/09/16 12:55
15	9	((US-6340113-$ or US-6199751-$ or US-6087021-$ or US-5812925-$ or US-5621607-$ or US-5542602-$ or US-5392982-$ or US-5025304-$ or US-5009360-$ or US-4325734-$).did.) and (below or lower or less) with (melt or melting or liqu$9) with (point or points or temperature or temperatures)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23
16	4	(US-5009360-$ or US-5621607-$ or US-5812925-$ or US-4325734-$).did.	USPAT	2003/09/16 13:03
17	4	((US-5009360-$ or US-5621607-$ or US-5812925-$ or US-4325734-$).did.) and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:16
18	1247	228/193-195.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:16
19	111	228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond$9 or join$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:22
20	80	228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus$9 or weld$9 or braz$9 or solder$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23

21	119	(228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond$9 or join$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus$9 or weld$9 or braz$9 or solder$9))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23
22	64	((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond$9 or join$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus$9 or weld$9 or braz$9 or solder$9))) and (below or lower or less) with (melt or melting or liqu$9) with (point or points or temperature or temperatures)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23
23	119	((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond$9 or join$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus$9 or weld$9 or braz$9 or solder$9))) or (((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond$9 or join$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus$9 or weld$9 or braz$9 or solder$9))) and (below or lower or less) with (melt or melting or liqu$9) with (point or points or temperature or temperatures))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:24